



IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

T.R. Cundiff et al.

Attorney Docket No.: BOCO122200

Application No.: 10/758,404

Art Unit: 1762 / Confirmation No.: 6099

Filed:

January 15, 2004

Examiner: C.I. Sellman

Title:

RESIN TRANSFER MOLDING PROCESS

AMENDMENT TRANSMITTAL LETTER

Seattle, Washington 98101

March 13, 2006

TO THE COMMISSIONER FOR PATENTS:

A. **Amendment Transmittal**

Transmitted herewith is an amendment in the above-identified application.

1. No additional claim fee is required, as shown below.

2. The claim fee has been calculated as shown below.

COMPUTATION OF FEE FOR CLAIMS AS AMENDED

	11 0 17 11 10 11 01								
	Claims		Highest						
	Remaining		Number						
	After		Previously		Present				Additional
	Amendment		Paid For		Extra		Rate		Fee
Total Claims	12	_	20	=	0	х	50	=	0
Independent Claims	2	-	3	=	0	X	200	=	0
	TOTAL								\$0

B. Additional Fee Charges or Credit for Overpayment

The Commissioner is hereby authorized to charge any fees under 37 C.F.R. §§ 1.16, 1.17 and 1.18 which may be required during the entire pendency of the application, or credit any overpayment, to Deposit Account No. 03-1740. This authorization also hereby includes a request for any extensions of time of the appropriate length required upon the filing of any reply during the entire prosecution of this application.

Respectfully submitted,

CHRISTENSEN O'CONNOR JOHNSON KINDNESSPLF

Gary S. Kindness

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I hereby certify that this correspondence is being deposited with the U.S. Postal Service in a sealed envelope as first class mail with postage thereon fully prepaid and addressed to Mail Stop Amendment, Commissioner for Patents, P.O. Box 1450, Alexandria, VA 22313-1450, on the below date.

Date:

3/13/2006

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GSK:aew





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AMENDMENT A

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INTRODUCTORY COMMENTS

Please amend the above-identified patent application as follows.